

RESPONSE AND AMENDMENT

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B1
a gas distribution plate disposed within said recess and having a plurality of blind radial grooves in a fluid communication with the center gas feed; and

a plurality of apertures disposed within said grooves and extending through the gas distribution plate.

18. (Amended) Apparatus for gas distribution in a semiconductor wafer processing chamber comprising:

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a roof having a top surface and a bottom surface and having a center gas feed;

a recess disposed within the bottom surface of said roof;

a gas distribution plate disposed within said recess and having a plurality of blind radial grooves in a fluid communication with the center gas feed; and

a material layer coating disposed upon the bottom surface of the roof and the gas distribution plate.

Please add new claim 26 as follows:

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26. (New) The apparatus of claim 13 wherein the apertures of the gas distribution plate coincide with the apertures in the material layer.

REMARKS

In the Office Action, the Examiner noted that claims 1-25 are pending in the application, the claims 2-5 are withdrawn from consideration, and that claims 1 and 6-25 are rejected. In view of the above amendments and the following discussion, the Applicants submit that none of the claims now pending in the application are indefinite under the provisions of 35 U.S.C. §112, anticipated under the provisions of 35 U.S.C. §102, or obvious under the provisions of 35 U.S.C. § 103. Thus, the Applicants believe that all of these claims are now in condition for allowance.

In particular, the Applicants have amended claims 1 and 18 for administrative purposes to better claim the invention. The above amendments to claims 1 and 18 are not made for patentability reasons. As discussed below, the Applicant believes claims 1